

Switch, SP2T 100 Watt Reflective 0.03 - 3.0 GHz

Rev. V1

Features

- Suitable for High Power Military and Civilian Radio Applications
- Power Handling: 100 W @ 85°C
- Insertion Loss: 0.35 dB @ 2 GHz
- Isolation: 51 dB @ 2 GHz
- Lead-Free 5 mm HQFN-12LD Package
- RoHS* Compliant and 260°C Reflow Compatible

Description

The MASW-011055 is a high power PIN diode SP2T switch in a common anode configuration, operating from 30 MHz to 3 GHz. It features low insertion loss and excellent linearity. This device is capable of handling 100 Watts CW incident power at a base plate temperature of 85°C.

This high power switch is ideal for use on land mobile radio and MIL-COM applications that require higher CW and pulsed power operation.

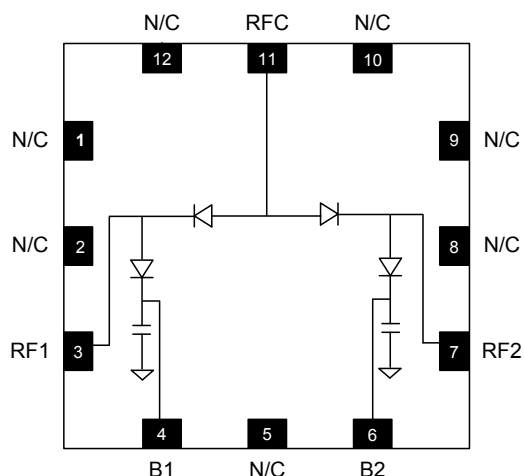
The MASW-011055 is manufactured using MACOM's hybrid manufacturing process featuring high voltage PIN diodes and passive devices integrated in a 5 mm HQFN 12-lead plastic package.

Ordering Information¹

Part Number	Package
MASW-011055-TR0500	500 piece reel
MASW-011055-SMB	Sample Board

1. Reference Application Note M513 for reel size information.

Functional Schematic



Pin Configuration

Pin	Function	Pin	Function
1	No Connection	7	RF2 / V2 Bias
2	No Connection	8	No Connection
3	RF1 / V1 Bias	9	No Connection
4	B1 Bias	10	No Connection
5	No Connection	11	RFC / V3 Bias
6	B2 Bias	12	No Connection
		Paddle ²	Ground

2. The exposed pad centered on the package bottom must be connected to RF, DC and thermal ground.

* Restrictions on Hazardous Substances, European Union Directive 2011/65/EU.

Switch, SP2T 100 Watt Reflective 0.03 - 3.0 GHz

Rev. V1

Electrical Specifications: $T_A = 25^\circ\text{C}$, Bias³ = +5 / -5 V, 50 mA / 100 mA

Parameter	Test Conditions	Units	Min.	Typ.	Max.
Insertion Loss $P_{IN} = 0 \text{ dBm}$	0.5 GHz 1 GHz 2 GHz	dB	—	0.10 0.20 0.35	— 0.50 —
Isolation $P_{IN} = 0 \text{ dBm}$	0.5 GHz 1 GHz 2 GHz	dB	— 48 —	52 54 51	—
Input Return Loss	$P_{IN} = 0 \text{ dBm}$	dB	—	>15	—
CW Input Power	25°C base plate, 2 GHz	dBm W	—	52 158	—
CW Input Power	85°C base plate, 2 GHz	dBm W	—	50 100	—
P0.1dB	25°C base plate, 2 GHz	dBm	—	>52	—
Input IP3	F1 = 2000 MHz, F2 = 2010 MHz $P_{IN} = 40 \text{ dBm/Tone}$, 28 V	dBm	—	66	—
RF Switching Speed	(10-90% RF Voltage) 1 MHz Rep Rate in Modulating Mode	ns	—	500	—

3. See Bias table.

Bias (+5 V / -5 V)

RF State	V1 Bias (V)	V2 Bias (V)	V3 Bias (V)	B1 Bias (V)	B2 Bias (V)
RFC – RF1 Low Loss RFC – RF2 Isolation	-5 V @ 100 mA	+5 V @ 50 mA	0 V	0 V	0 V
RFC – RF2 Low Loss RFC – RF1 Isolation	+5 V @ 50 mA	-5 V @ 100 mA	0 V	0 V	0 V

4. DC reverse bias of a PIN Diode operating at a high power is dependent on RF frequency, incident power, and VSWR. See Minimum Reverse DC Voltage table for high power operation.

Switch, SP2T 100 Watt Reflective 0.03 - 3.0 GHz

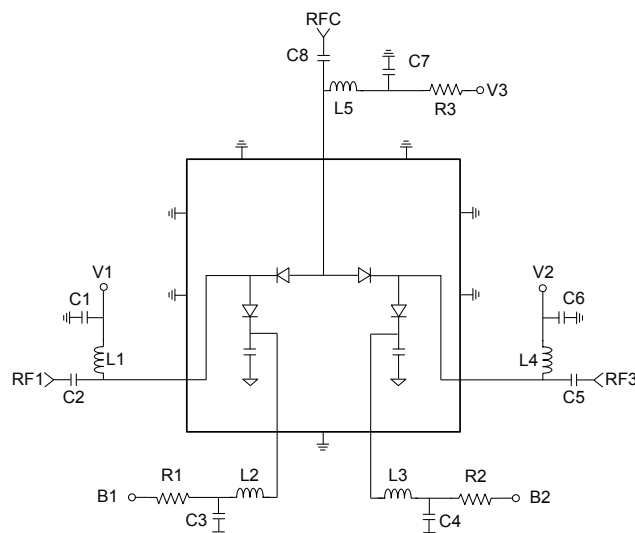
Rev. V1

Minimum Reverse DC Voltage⁵

Frequency (MHz)	Minimum Reverse DC Voltage
30	-120 V
100	-119 V
200	-114 V
300	-106 V
500	-90 V
1000	-59 V
1500	-43 V
2000	-33 V

5. Required to maintain low loss under 100 W of incident power with 1.5:1 VSWR.

Application Schematic



Absolute Maximum Ratings^{6,7}

Parameter	Absolute Maximum
Forward Current	200 mA
Reverse DC Voltage	-150 V
Operating Temperature	-40°C to +85°C
Storage Temperature	-55°C to +150°C
Junction Temperature	+175°C

6. Exceeding any one or combination of these limits may cause permanent damage to this device.
7. MACOM does not recommend sustained operation near these survivability limits.

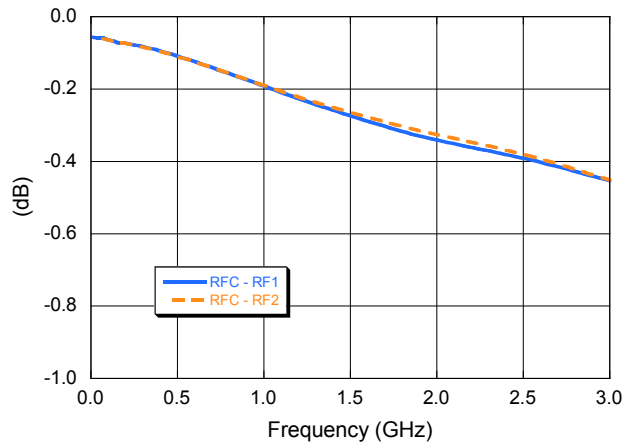
Off-Chip Component Values

Component	Operating Frequency		Size
	0.03 - 1.0 GHz	0.5 - 3.0 GHz	
C1, C3, C4, C6, C7, C8	0.1 μ F	270 pF	0603
C2, C5, C8	0.1 μ F	27 pF	0603
L1 - L5	3.3 μ H	82 nH	0603
R1 - R2 ⁸	82 Ω	82 Ω	1210
R3 ⁸	39 Ω	39 Ω	1210

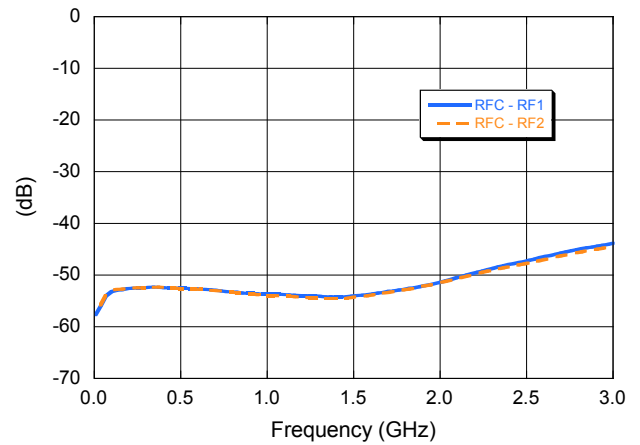
8. Resistance values are used for small signal testing under +5 V / -5 V bias conditions.

Typical Performance Curves @ +25°C (using external bias tees):

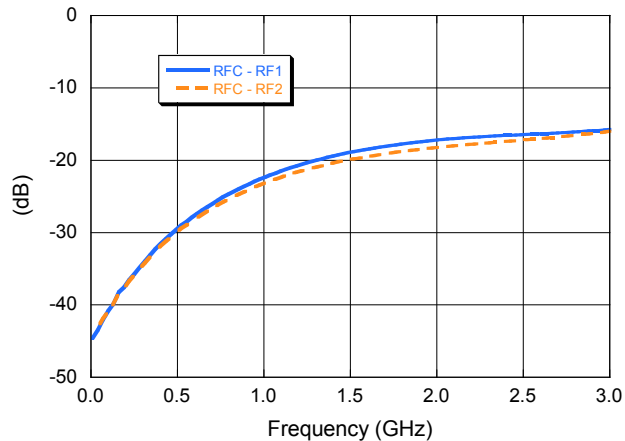
Insertion Loss



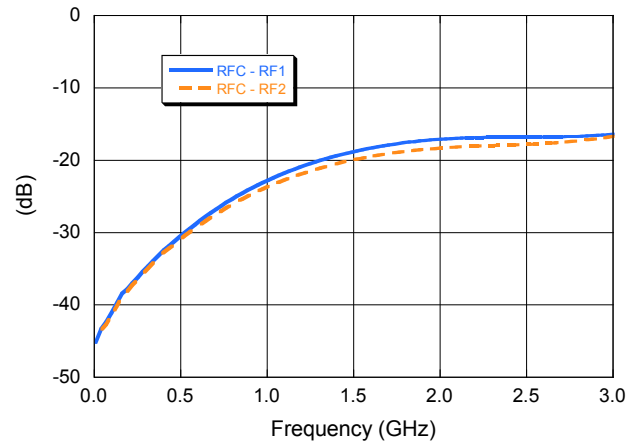
Isolation



Input Return Loss



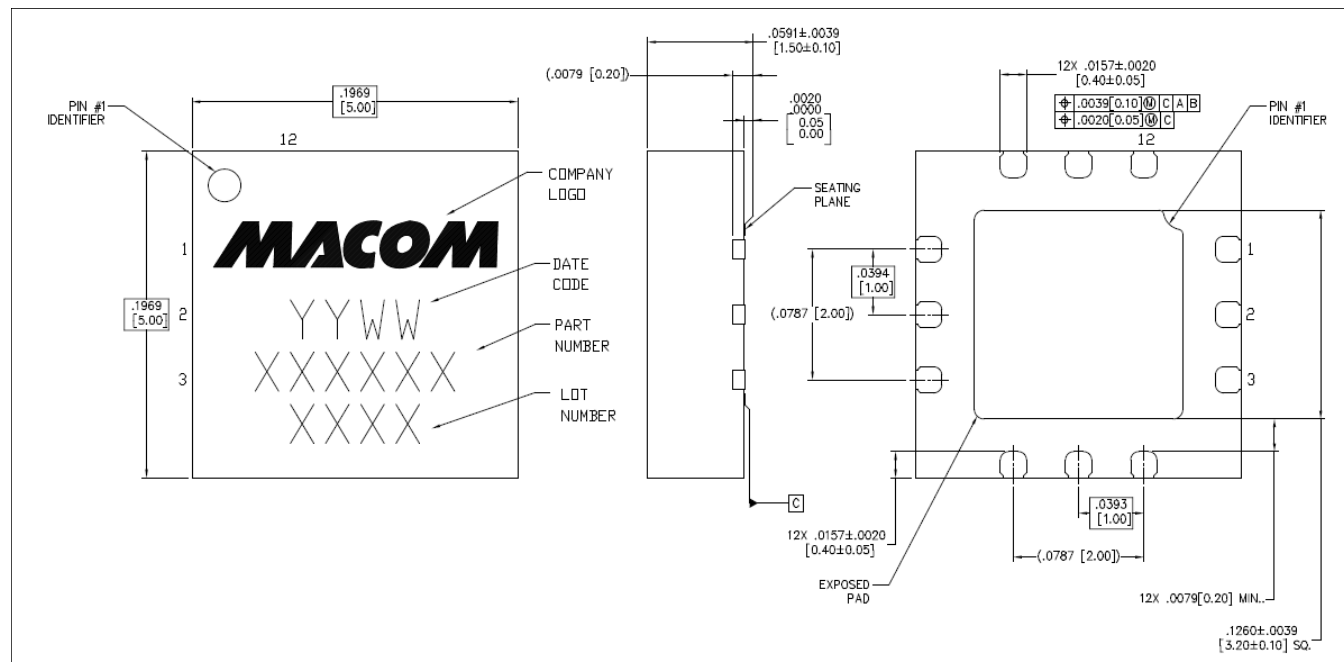
Output Return Loss



Switch, SP2T 100 Watt Reflective
0.03 - 3.0 GHz

Rev. V1

Lead Free 5 mm 12-Lead HQFN [†]



[†] Reference Application Note S2083 for lead-free solder reflow recommendations.
Meets JEDEC moisture sensitivity level 1 requirements.
Plating is NiPdAuAg.

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

Silicon Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these Class 1B HBM devices.